

AUIRFZ46NS

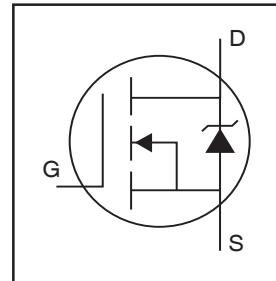
AUIRFZ46NL

Features

- Advanced Planar Technology
- Low On-Resistance
- Dynamic dV/dT Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to T_{jmax}
- Lead-Free, RoHS Compliant
- Automotive Qualified *

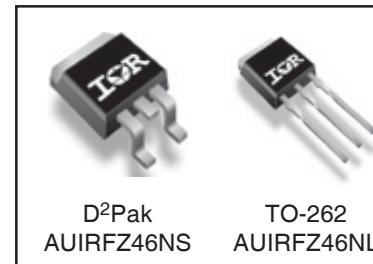
Description

Specifically designed for Automotive applications, this stripe planar design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.



HEXFET® Power MOSFET

$V_{(BR)DSS}$	55V
$R_{DS(on)}$ max.	16.5mΩ
I_D (Silicon Limited)	53A ^⑦
I_D (Package Limited)	39A



G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I_D @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	53 ^⑦	A
I_D @ $T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	37	
I_D @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Package Limited)	39	
I_{DM}	Pulsed Drain Current ^{①⑨}	180	
P_D @ $T_A = 25^\circ\text{C}$	Power Dissipation	3.8	W
P_D @ $T_C = 25^\circ\text{C}$	Power Dissipation	107	
	Linear Derating Factor	0.71	
V_{GS}	Gate-to-Source Voltage	±20	
E_{AS}	Single Pulse Avalanche Energy ^{②⑩}	152	mJ
I_{AR}	Avalanche Current ^①	28	A
E_{AR}	Repetitive Avalanche Energy ^①	11	mJ
dv/dt	Peak Diode Recovery dv/dt ^{③⑪}	5.0	V/ns
T_J	Operating Junction and	-55 to + 175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{θJC}$	Junction-to-Case	—	1.4	°C/W
$R_{θJA}$	Junction-to-Ambient (PCB mounted, steady-state) ^⑫	—	40	

HEXFET® is a registered trademark of International Rectifier.

*Qualification standards can be found at <http://www.irf.com/>

www.irf.com

Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	55	—	—	V	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.057	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1\text{mA}$ ⑤
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	16.5	$\text{m}\Omega$	$V_{\text{GS}} = 10\text{V}$, $I_D = 28\text{A}$ ④
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$
g_{fs}	Forward Transconductance	19	—	—	S	$V_{\text{DS}} = 25\text{V}$, $I_D = 28\text{A}$ ④ ⑤
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{\text{DS}} = 55\text{V}$, $V_{\text{GS}} = 0\text{V}$
		—	—	250		$V_{\text{DS}} = 44\text{V}$, $V_{\text{GS}} = 0\text{V}$, $T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{\text{GS}} = 20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}} = -20\text{V}$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Q_g	Total Gate Charge	—	—	72	nC	$I_D = 28\text{A}$ $V_{\text{DS}} = 44\text{V}$ $V_{\text{GS}} = 10\text{V}$, See Fig.6 and 13 ④ ⑤
Q_{gs}	Gate-to-Source Charge	—	—	11		
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	26		
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	14	—	ns	$V_{\text{DD}} = 28\text{V}$ $I_D = 28\text{A}$ $R_G = 12\Omega$ $R_D = 0.98\Omega$, See Fig. 10 ④ ⑤
t_r	Rise Time	—	76	—		
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	52	—		
t_f	Fall Time	—	57	—		
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.)
L_S	Internal Source Inductance	—	7.5	—		Between lead, and center of die contact
C_{iss}	Input Capacitance	—	1696	—		$V_{\text{GS}} = 0\text{V}$
C_{oss}	Output Capacitance	—	407	—	pF	$V_{\text{DS}} = 25\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	110	—		$f = 1.0\text{MHz}$, See Fig.5 ⑤

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	53⑦	A	MOSFET symbol showing the integral reverse p-n junction diode.
	Pulsed Source Current (Body Diode) ①	—	—	180		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}$, $I_S = 28\text{A}$, $V_{\text{GS}} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	67	101	ns	$T_J = 25^\circ\text{C}$, $I_F = 28\text{A}$
Q_{rr}	Reverse Recovery Charge	—	208	312	nC	$\text{di}/\text{dt} = 100\text{A}/\mu\text{s}$ ④ ⑤
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting $T_J = 25^\circ\text{C}$, $L = 389\mu\text{H}$, $R_G = 25\Omega$, $I_{\text{AS}} = 28\text{A}$. (See Figure 12)
- ③ $I_{\text{SD}} \leq 28\text{A}$, $\text{di}/\text{dt} \leq 220\text{A}/\mu\text{s}$, $V_{\text{DD}} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$.
- ④ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑤ Uses IRFZ46N data and test conditions.
- ⑥ This is a calculated value limited to $T_J = 175^\circ\text{C}$.
- ⑦ Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 39A.
- ⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ^{††}	
Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.			
Moisture Sensitivity Level	3L-D2 PAK	MSL1	
	3L-TO-262	N/A	
ESD	Machine Model	Class M3(+/- 400V) (per AEC-Q101-002)	
	Human Body Model	Class H1B(+/- 1000V) (per AEC-Q101-001)	
	Charged Device Model	Class C5(+/- 2000V) (per AEC-Q101-005)	
RoHS Compliant		Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/>

^{††} Exceptions to AEC-Q101 requirements are noted in the qualification report.

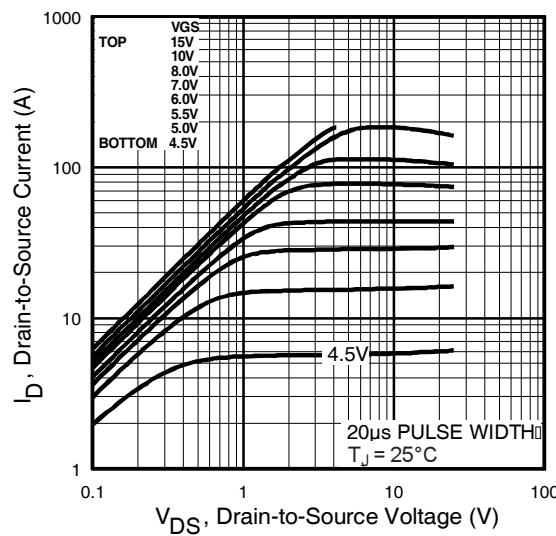


Fig 1. Typical Output Characteristics

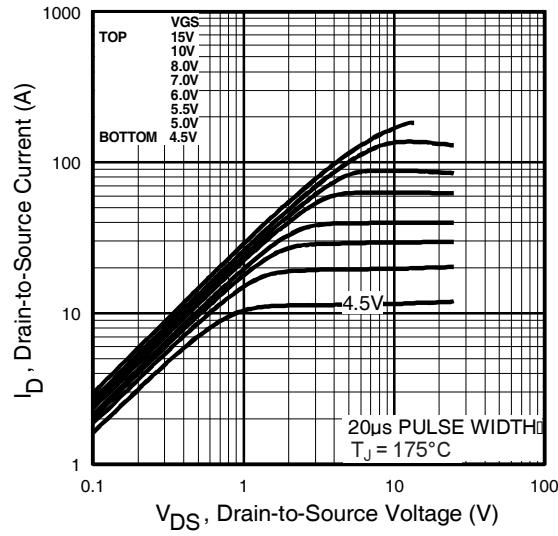


Fig 2. Typical Output Characteristics

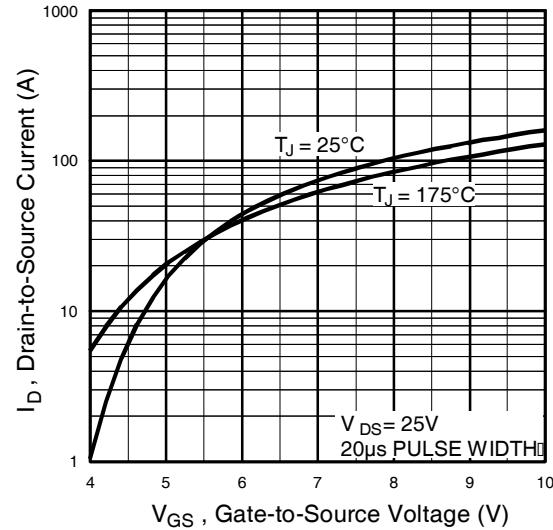


Fig 3. Typical Transfer Characteristics

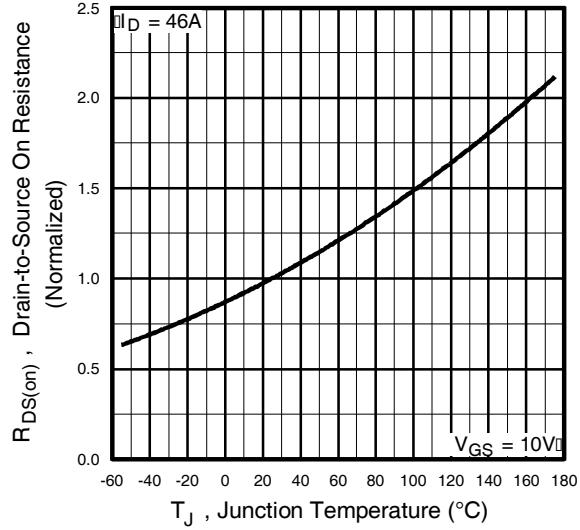


Fig 4. Normalized On-Resistance
Vs. Temperature

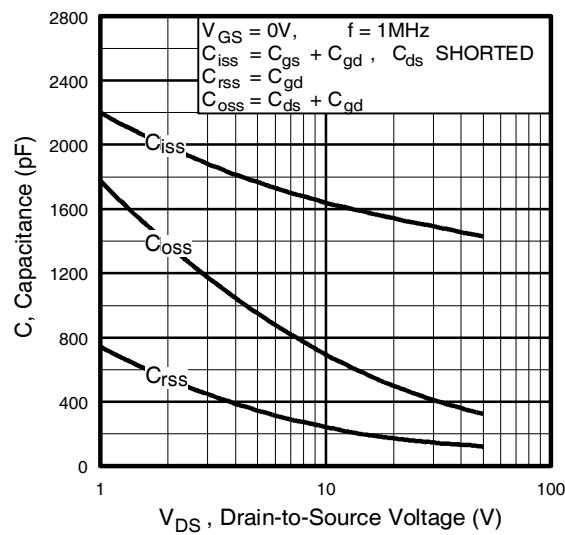


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

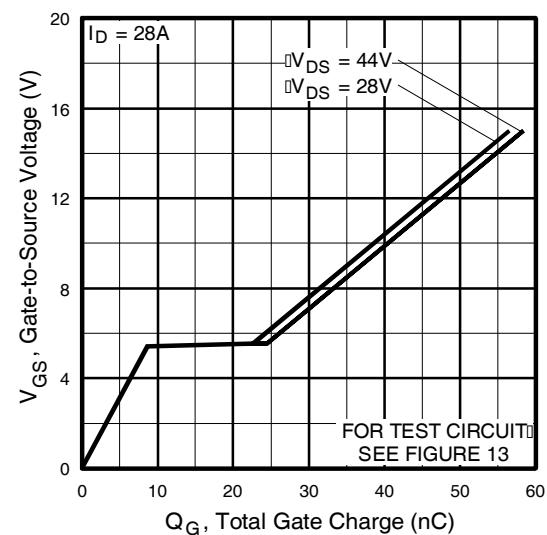


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

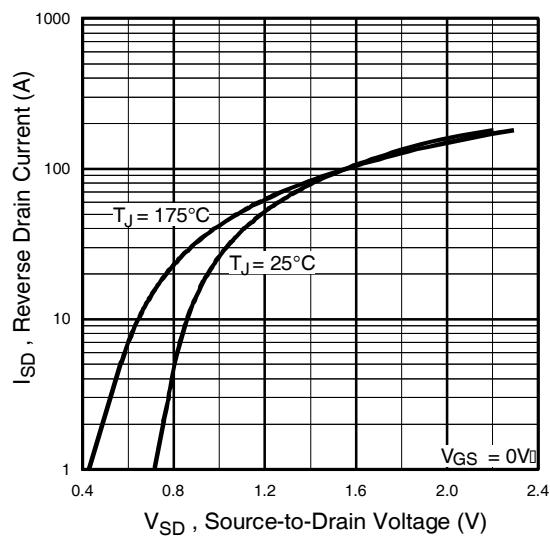


Fig 7. Typical Source-Drain Diode
Forward Voltage

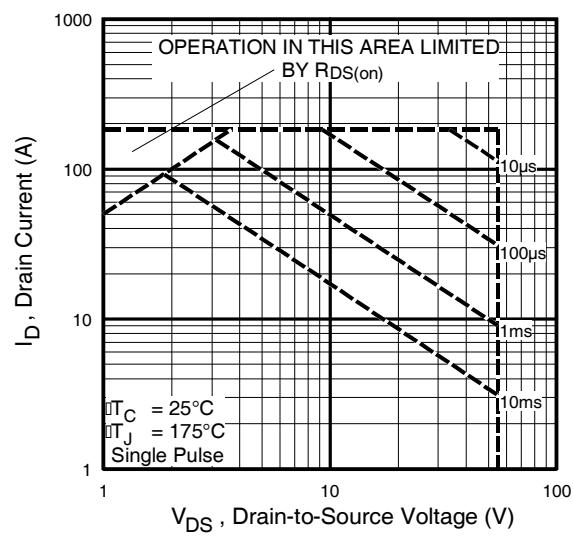


Fig 8. Maximum Safe Operating Area

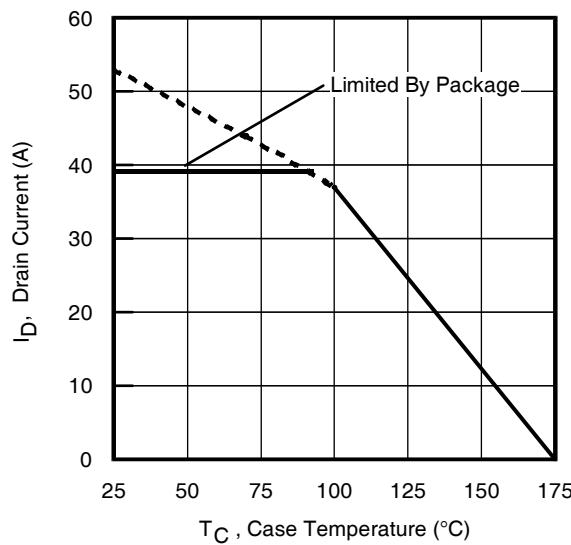


Fig 9. Maximum Drain Current Vs.
Case Temperature

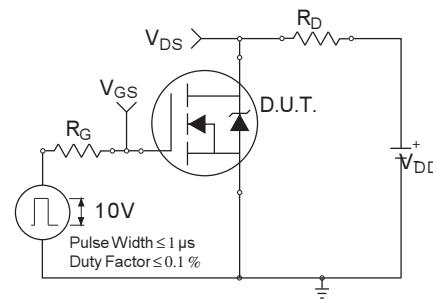


Fig 10a. Switching Time Test Circuit

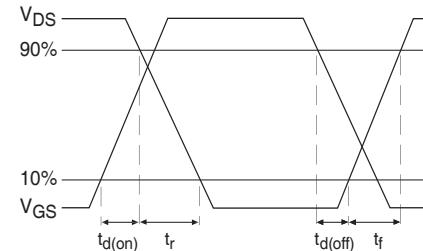


Fig 10b. Switching Time Waveforms

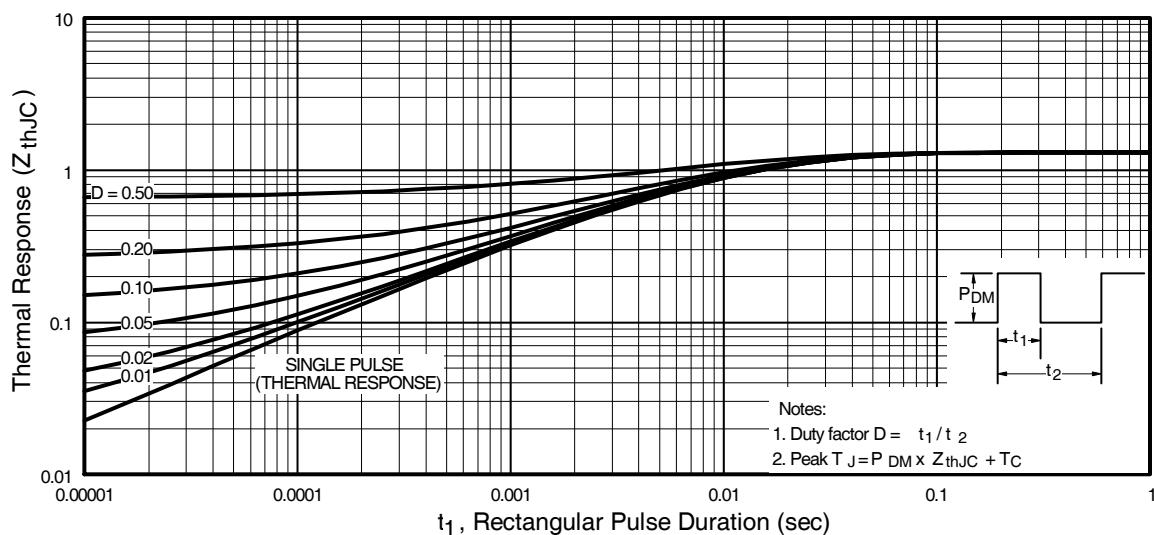


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

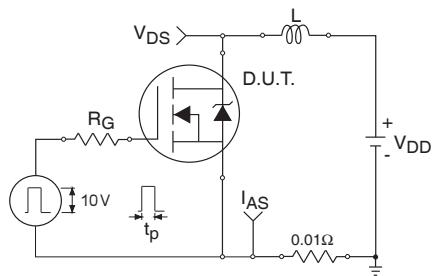


Fig 12a. Unclamped Inductive Test Circuit

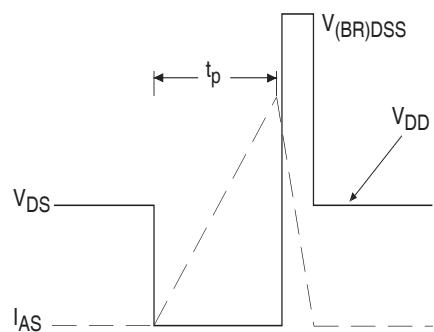


Fig 12b. Unclamped Inductive Waveforms

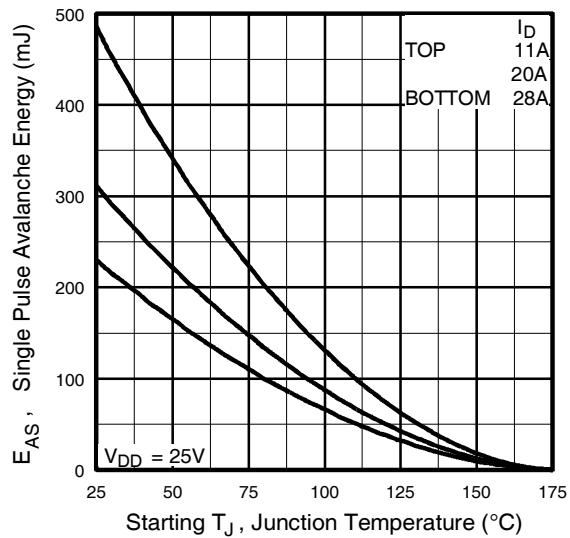


Fig 12c. Maximum Avalanche Energy
Vs. Drain Current

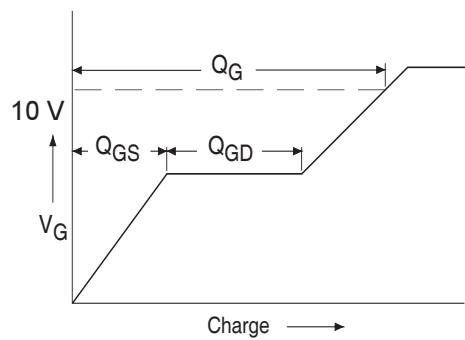


Fig 13a. Basic Gate Charge Waveform

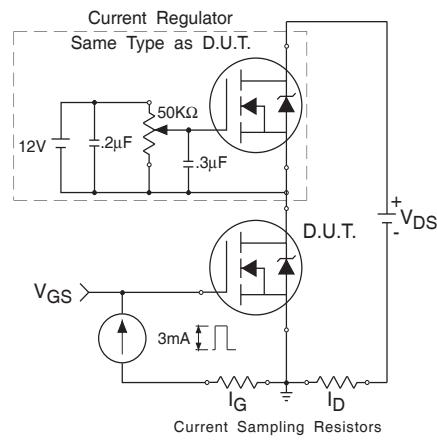
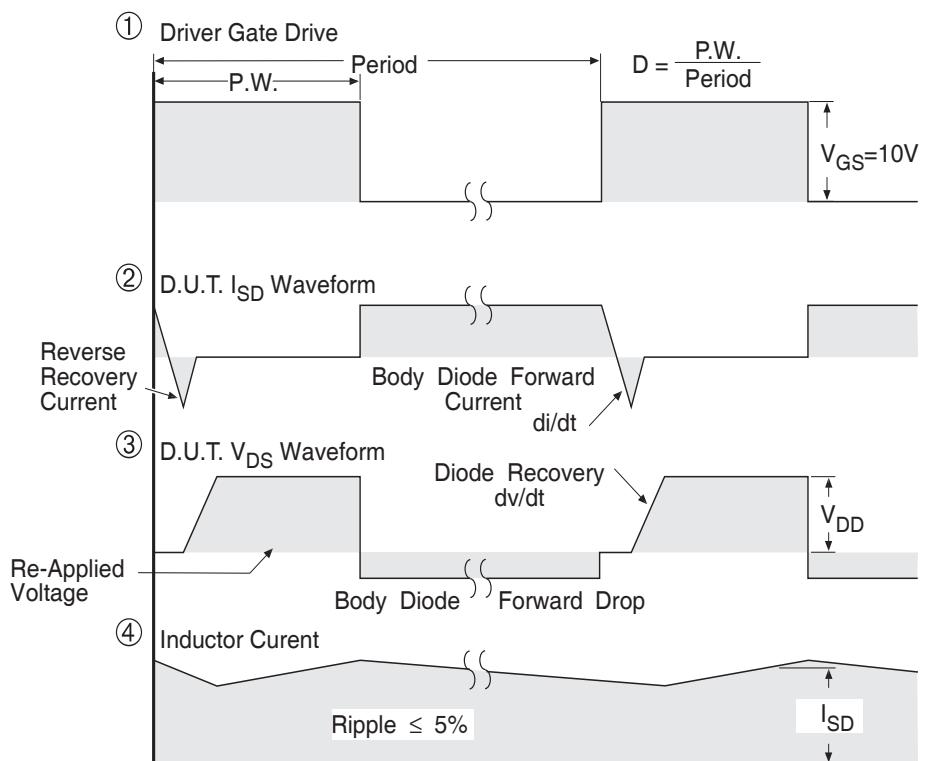
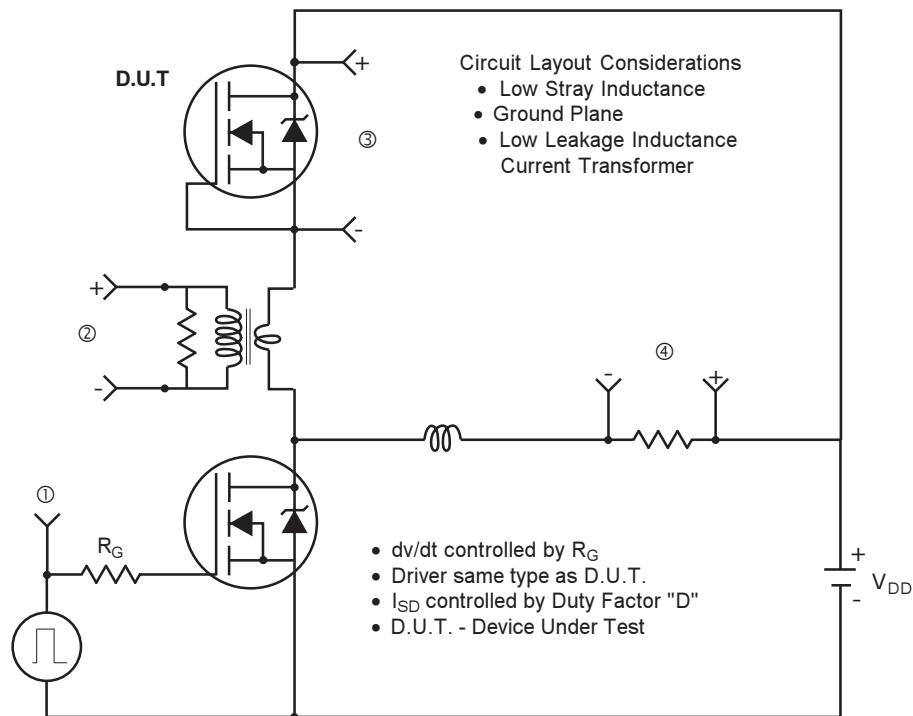


Fig 13b. Gate Charge Test Circuit

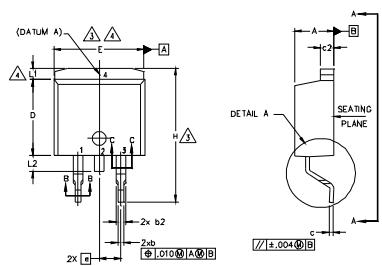
Peak Diode Recovery dv/dt Test Circuit



* $V_{GS} = 5V$ for Logic Level Devices

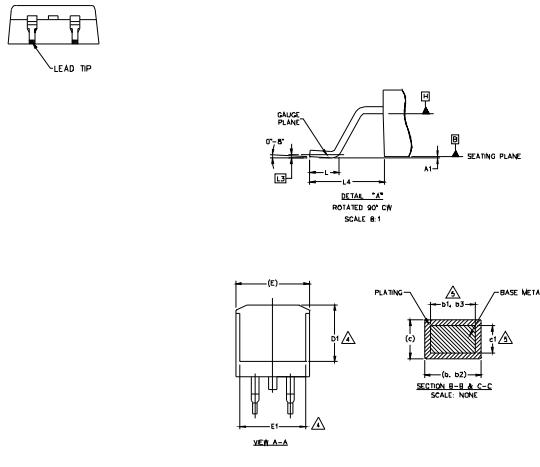
Fig 14. For N-Channel HEXFETs

D²Pak Package Outline (Dimensions are shown in millimeters (inches))



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
7. CONTROLLING DIMENSION: INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263AB.



S Y M B O L	DIMENSIONS				N O T E S	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	4.06	4.83	.160	.190		
A1	0.00	0.254	.000	.010		
b	0.51	0.99	.020	.039		
b1	0.51	0.89	.020	.035	5	
b2	1.14	1.78	.045	.070		
b3	1.14	1.73	.045	.068	5	
c	0.38	0.74	.015	.029		
c1	0.38	0.58	.015	.023	5	
c2	1.14	1.65	.045	.065		
D	8.38	9.65	.330	.380	3	
D1	6.86	—	.270	—	4	
E	9.65	10.67	.380	.420	3,4	
E1	6.22	—	.245	—	4	
e	2.54	BSC	.100	BSC		
H	14.61	15.88	.575	.625		
L	1.78	2.79	.070	.110		
L1	—	1.65	—	.066		
L2	1.27	1.78	—	.070		
L3	0.25	BSC	.010	BSC		
L4	4.78	5.28	.188	.208		

LEAD ASSIGNMENTS

HEXFET

1. – GATE
2. 4. – DRAIN
3. – SOURCE

IGBTs, CoPACK

1. – GATE
2. 4. – COLLECTOR
3. – Emitter

DIODES

1. – ANODE *
2. 4. – CATHODE
3. – ANODE

* PART DEPENDENT.

D²Pak Part Marking Information

Part Number

AUFZ46NS

Date Code

Y= Year

WW= Work Week

A= Automotive, Lead Free

IR Logo

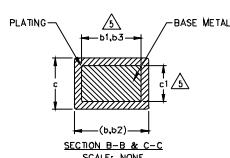
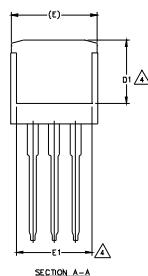
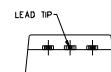
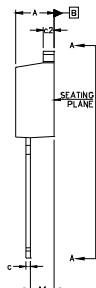
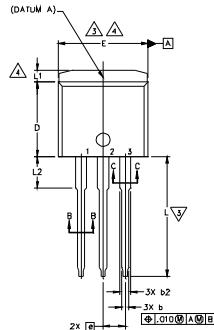
IR YWWA

XX ● XX

Lot Code

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

TO-262 Package Outline (Dimensions are shown in millimeters (inches))



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION: INCH.
7. OUTLINE CONFORM TO JEDEC TO-262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

S Y M B O L	DIMENSIONS				N O T E S	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	4.06	4.83	.160	.190		
A1	2.03	3.02	.080	.119		
b	0.51	0.99	.020	.039		
b1	0.51	0.89	.020	.035	5	
b2	1.14	1.78	.045	.070		
b3	1.14	1.73	.045	.068	5	
c	0.38	0.74	.015	.029		
c1	0.38	0.58	.015	.023	5	
c2	1.14	1.65	.045	.065		
D	8.38	9.65	.330	.380	3	
D1	6.86	—	.270	—	4	
E	9.65	10.67	.380	.420	3,4	
E1	6.22	—	.245	—	4	
e	2.54	BSC	.100	BSC		
L	13.46	14.10	.530	.555		
L1	—	1.65	—	.065	4	
L2	3.56	3.71	.140	.146		

LEAD ASSIGNMENTS

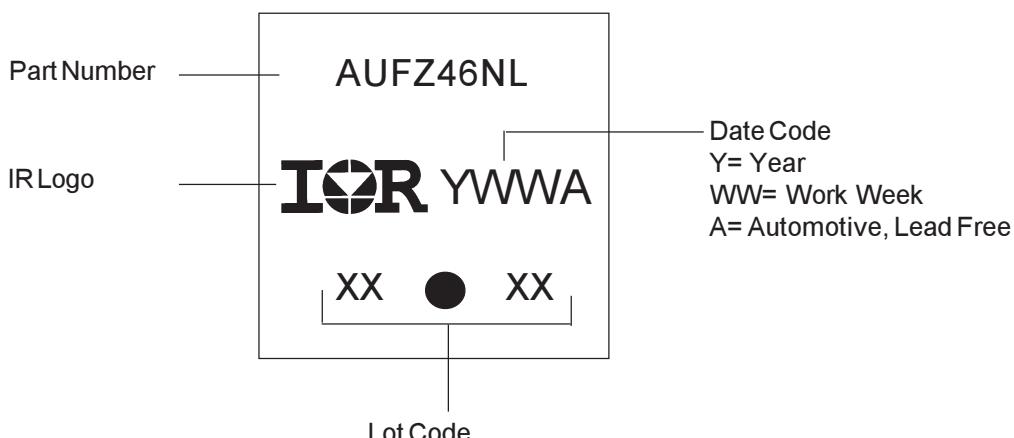
HEXFET

1. GATE
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IGBTs, CoPACK

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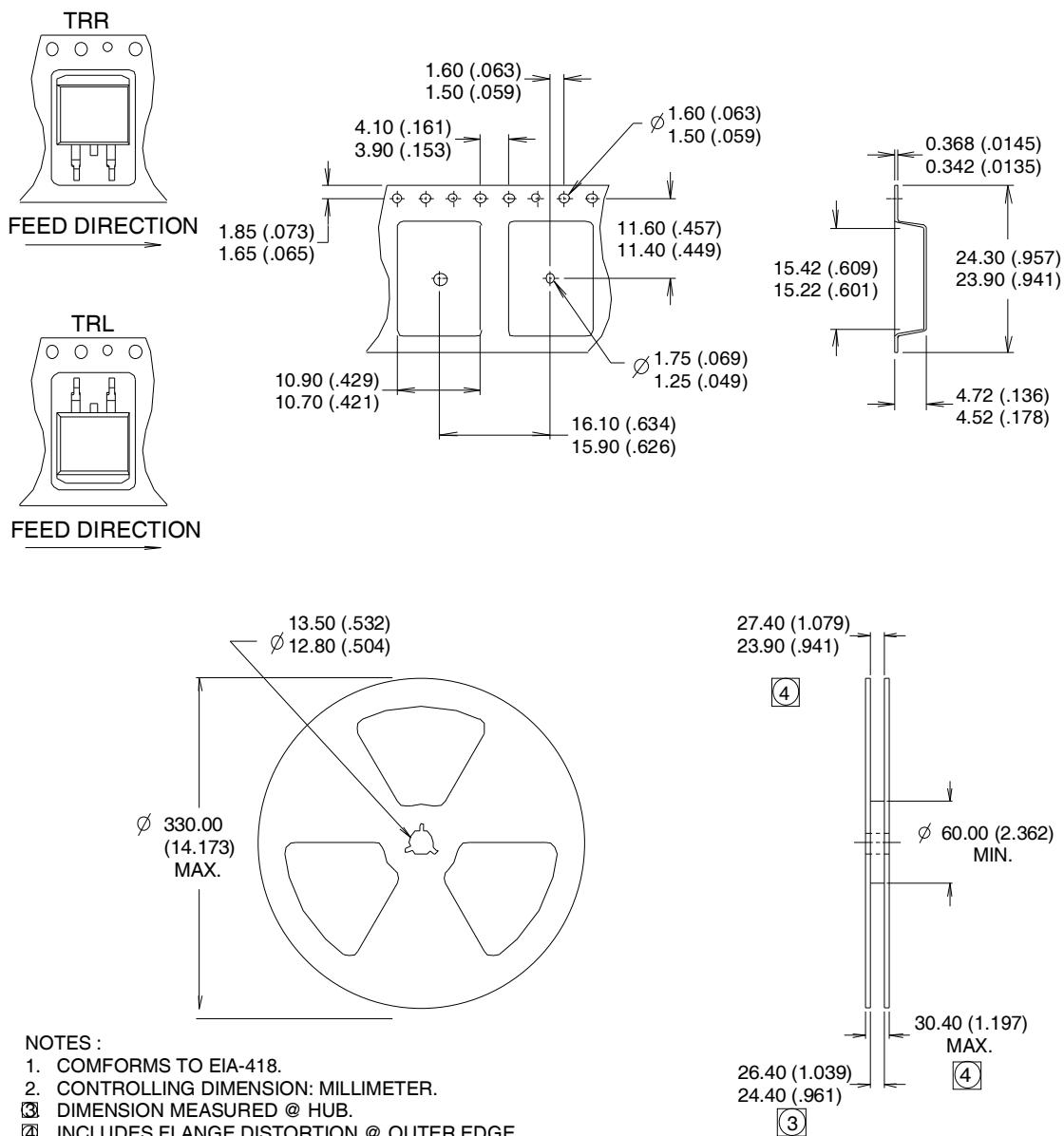
TO-262 Part Marking Information



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

D²Pak Tape & Reel Information

Dimensions are shown in millimeters (inches)



Ordering Information

Base part	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRFZ46NL	TO-262	Tube	50	AUIRFZ46NL
AUIRFZ46NS	D2Pak	Tube	50	AUIRFZ46NS
		Tape and Reel Left	800	AUIRFZ46NSTRL
		Tape and Reel Right	800	AUIRFZ46NSTRR

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IR warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with IR's standard warranty. Testing and other quality control techniques are used to the extent IR deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

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For technical support, please contact IR's Technical Assistance Center
<http://www.irf.com/technical-info/>

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